# Advanced Power MOSFET

# SFP9630

## FEATURES

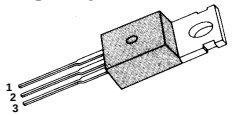
- Avalanche Rugged Technology
- Rugged Gate Oxide Technology
- Lower Input Capacitance
- Improved Gate Charge
- Extended Safe Operating Area
- Lower Leakage Current : -10 μA (Max.) @ $V_{DS}$ = -200V
- Low $R_{DS(ON)}$ : 0.581 Ω (Typ.)

$BV_{DSS}$ = -200 V

$R_{DS(on)}$ = 0.8 Ω

$I_D$ = -6.5 A

**TO-220**




**1.Gate 2. Drain 3. Source**

## Absolute Maximum Ratings

| Symbol | Characteristic | Value | Units |
|---|---|---|---|
| $V_{DSS}$ | Drain-to-Source Voltage | -200 | V |
| $I_D$ | Continuous Drain Current ($T_C$=25°C) | -6.5 | A |
| | Continuous Drain Current ($T_C$=100°C) | -4.0 | |
| $I_{DM}$ | Drain Current-Pulsed ① | -26 | A |
| $V_{GS}$ | Gate-to-Source Voltage | ± 30 | V |
| $E_{AS}$ | Single Pulsed Avalanche Energy ② | 563 | mJ |
| $I_{AR}$ | Avalanche Current ① | -6.5 | A |
| $E_{AR}$ | Repetitive Avalanche Energy ① | 7.0 | mJ |
| dv/dt | Peak Diode Recovery dv/dt ③ | -5.0 | V/ns |
| $P_D$ | Total Power Dissipation ($T_C$=25°C) | 70 | W |
| | Linear Derating Factor | 0.56 | W/°C |
| $T_J$ , $T_{STG}$ | Operating Junction and Storage Temperature Range | - 55 to +150 | °C |
| $T_L$ | Maximum Lead Temp. for Soldering Purposes, 1/8 " from case for 5-seconds | 300 | |

## Thermal Resistance

| Symbol | Characteristic | Typ. | Max. | Units |
|---|---|---|---|---|
| $R_{\theta JC}$ | Junction-to-Case | -- | 1.79 | °C/W |
| $R_{\theta CS}$ | Case-to-Sink | 0.5 | -- | |
| $R_{\theta JA}$ | Junction-to-Ambient | -- | 62.5 | |



FAIRCHILD SEMICONDUCTOR™

## Electrical Characteristics ($T_C$=25°C unless otherwise specified)

| Symbol | Characteristic | Min. | Typ. | Max. | Units | Test Condition |
|---|---|---|---|---|---|---|
| $BV_{DSS}$ | Drain-Source Breakdown Voltage | -200 | -- | -- | V | $V_{GS}$=0V,$I_D$=-250μA |
| $\Delta BV/\Delta T_J$ | Breakdown Voltage Temp. Coeff. | -- | -0.17 | -- | V/°C | $I_D$=-250μA ***See Fig 7*** |
| $V_{GS(th)}$ | Gate Threshold Voltage | -2.0 | -- | -4.0 | V | $V_{DS}$=-5V,$I_D$=-250μA |
| $I_{GSS}$ | Gate-Source Leakage , Forward | -- | -- | -100 | nA | $V_{GS}$=-30V |
| | Gate-Source Leakage , Reverse | -- | -- | 100 | | $V_{GS}$=30V |
| $I_{DSS}$ | Drain-to-Source Leakage Current | -- | -- | -10 | μA | $V_{DS}$=-200V |
| | | -- | -- | -100 | | $V_{DS}$=-160V,$T_C$=125°C |
| $R_{DS(on)}$ | Static Drain-Source On-State Resistance | -- | -- | 0.8 | Ω | $V_{GS}$=-10V,$I_D$=-3.3A ④ |
| $g_{fs}$ | Forward Transconductance | -- | 4.2 | -- | Ω | $V_{DS}$=-40V,$I_D$=-3.3A ④ |
| $C_{iss}$ | Input Capacitance | -- | 740 | 965 | pF | $V_{GS}$=0V,$V_{DS}$=-25V,f =1MHz ***See Fig 5*** |
| $C_{oss}$ | Output Capacitance | -- | 125 | 185 | | |
| $C_{rss}$ | Reverse Transfer Capacitance | -- | 49 | 75 | | |
| $t_{d(on)}$ | Turn-On Delay Time | -- | 14 | 35 | ns | $V_{DD}$=-100V,$I_D$=-6.5A, $R_G$=12Ω ***See Fig 13*** ④ ⑤ |
| $t_r$ | Rise Time | -- | 22 | 55 | | |
| $t_{d(off)}$ | Turn-Off Delay Time | -- | 41 | 90 | | |
| $t_f$ | Fall Time | -- | 17 | 45 | | |
| $Q_g$ | Total Gate Charge | -- | 29 | 36 | nC | $V_{DS}$=-160V,$V_{GS}$=-10V, $I_D$=-6.5A ***See Fig 6 & Fig 12*** ④ ⑤ |
| $Q_{gs}$ | Gate-Source Charge | -- | 5.8 | -- | | |
| $Q_{gd}$ | Gate-Drain( " Miller " ) Charge | -- | 13.6 | -- | | |

## Source-Drain Diode Ratings and Characteristics

| Symbol | Characteristic | Min. | Typ. | Max. | Units | Test Condition |
|---|---|---|---|---|---|---|
| $I_S$ | Continuous Source Current | -- | -- | -6.5 | A | Integral reverse pn-diode in the MOSFET |
| $I_{SM}$ | Pulsed-Source Current ① | -- | -- | -26 | | |
| $V_{SD}$ | Diode Forward Voltage ④ | -- | -- | -5.0 | V | $T_J$=25°C,$I_S$=-6.5A,$V_{GS}$=0V |
| $t_{rr}$ | Reverse Recovery Time | -- | 160 | -- | ns | $T_J$=25°C,$I_F$=-6.5A |
| $Q_{rr}$ | Reverse Recovery Charge | -- | 0.96 | -- | μC | $di_F/dt$=100A/μs ④ |

**Notes ;**

① Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature

② L=20mH, $I_{AS}$=-6.5A, $V_{DD}$=-50V, $R_G$=27Ω*, Starting $T_J$=25°C

③ $I_{SD}$ ≤-6.5A, di/dt≤400A/μs, $V_{DD}$≤$BV_{DSS}$ , Starting $T_J$=25°C

④ Pulse Test : Pulse Width = 250 μs, Duty Cycle ≤2%

⑤ Essentially Independent of Operating Temperature

**Fig 1. Output Characteristics**

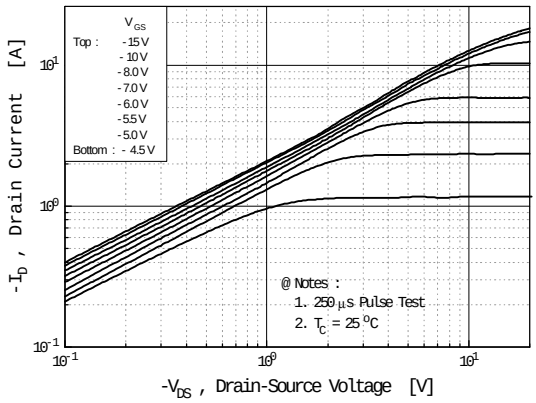



**Fig 2. Transfer Characteristics**

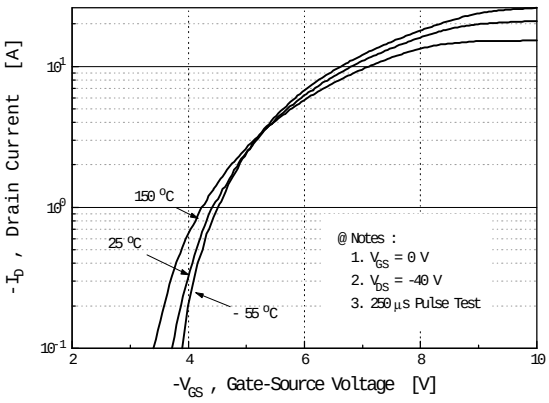



**Fig 3. On-Resistance vs. Drain Current**

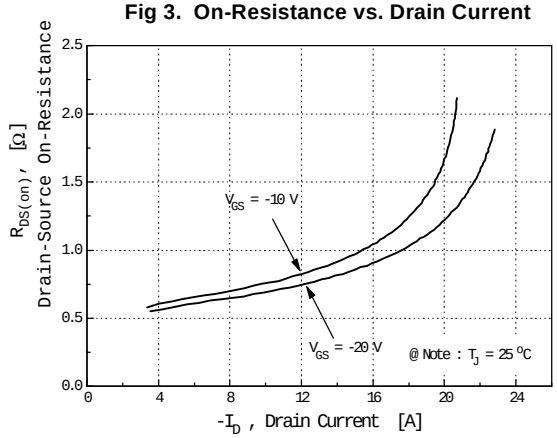



**Fig 4. Source-Drain Diode Forward Voltage**

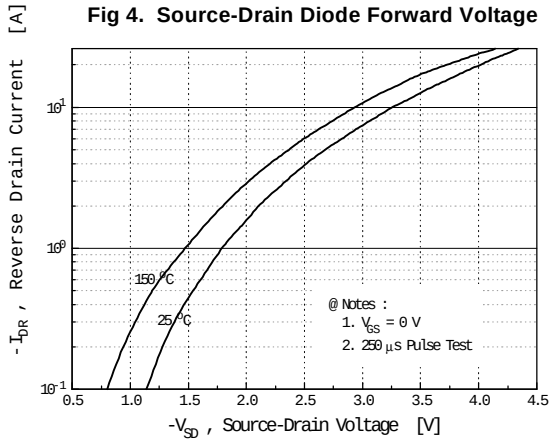



**Fig 5. Capacitance vs. Drain-Source Voltage**

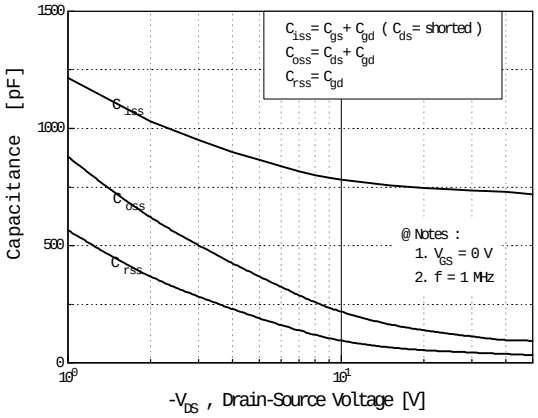



**Fig 6. Gate Charge vs. Gate-Source Voltage**

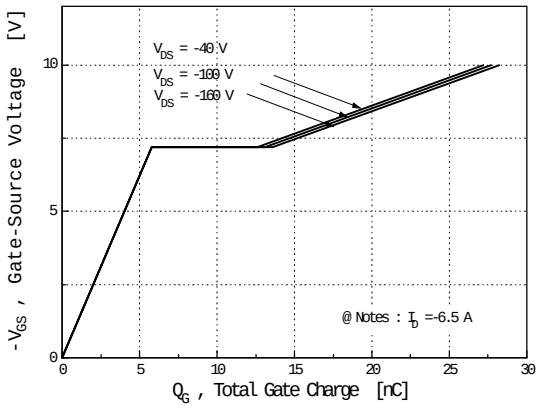


**Fig 7. Breakdown Voltage vs. Temperature**

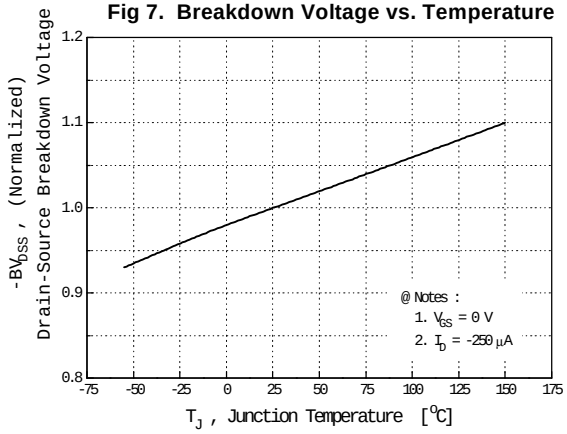



**Fig 8. On-Resistance vs. Temperature**

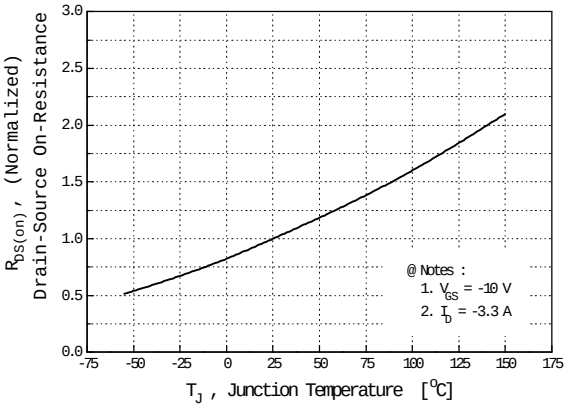



**Fig 9. Max. Safe Operating Area**

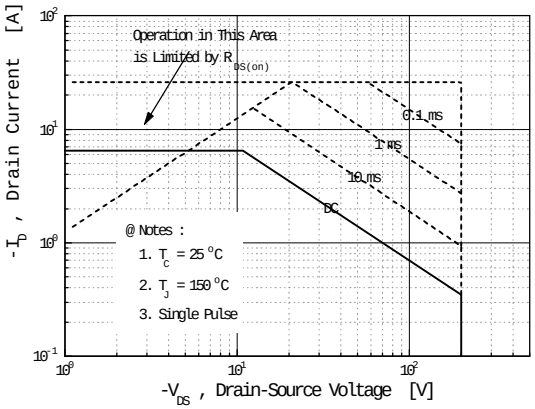



**Fig 10. Max. Drain Current vs. Case Temperature**

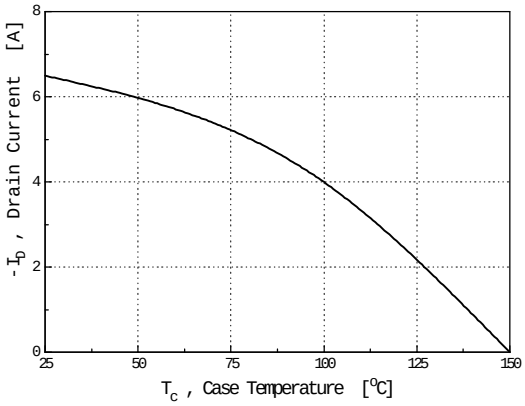



**Fig 11. Thermal Response**

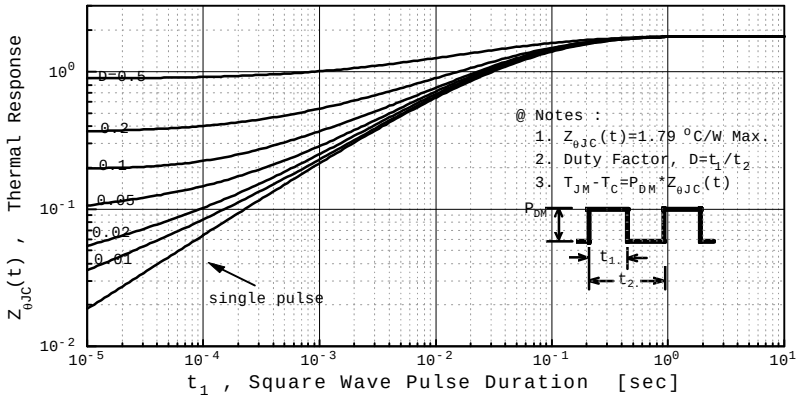


**Fig 12. Gate Charge Test Circuit & Waveform**

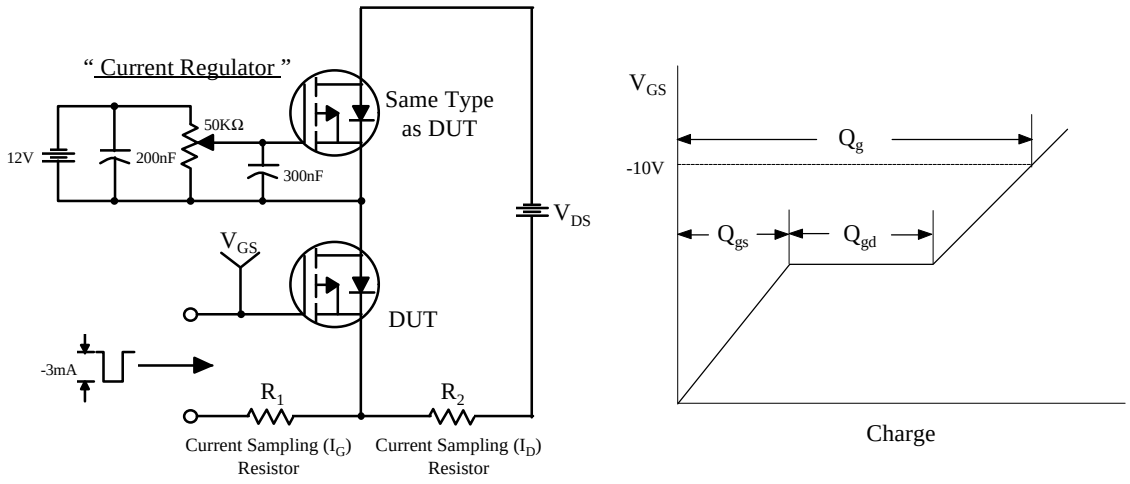



**Fig 13. Resistive Switching Test Circuit & Waveforms**

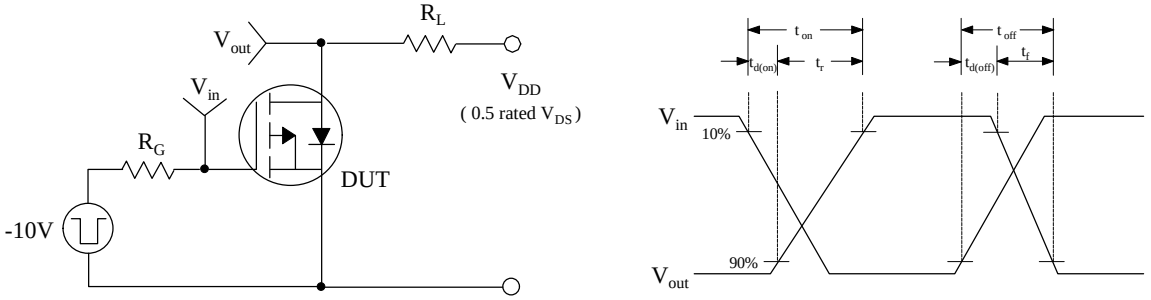



**Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms**

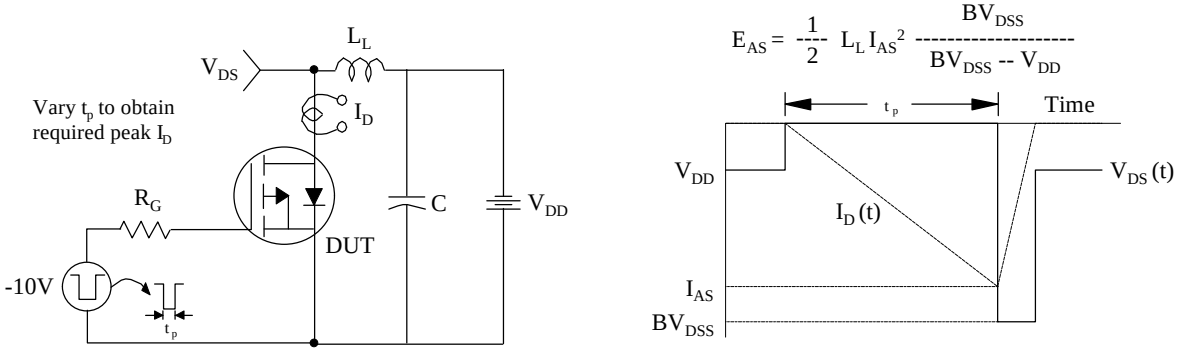
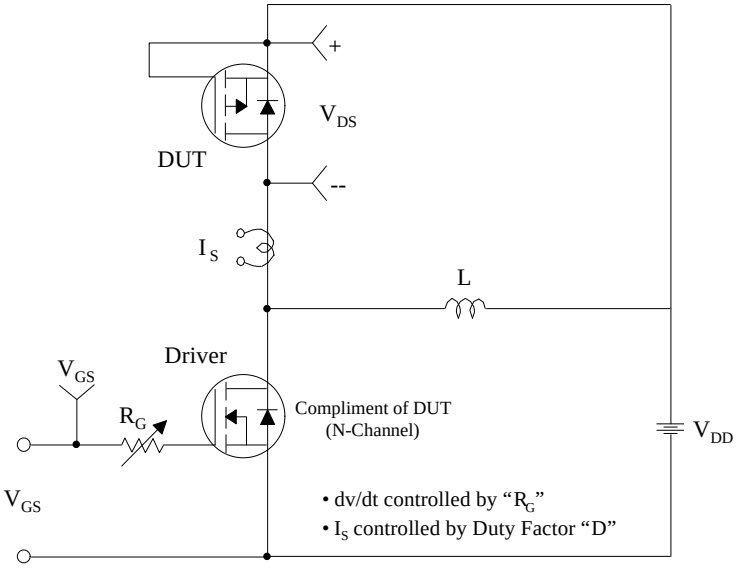
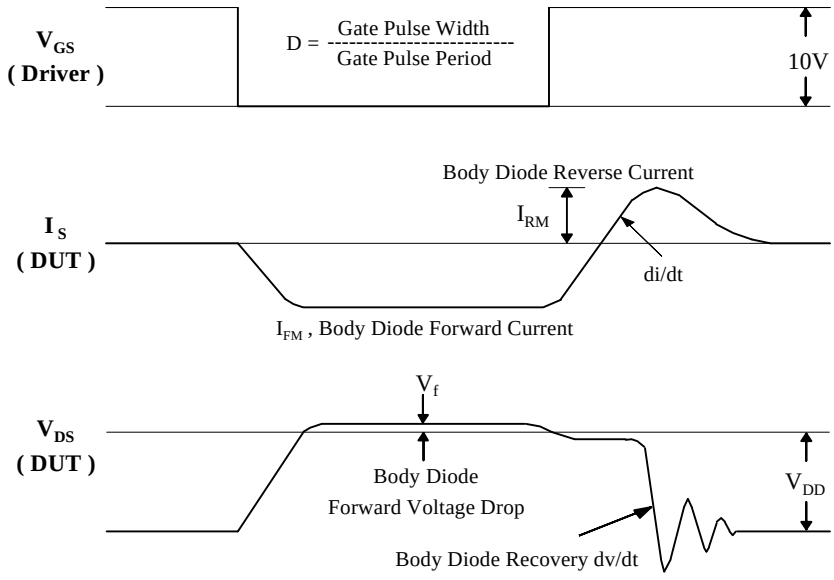


**Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms**



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